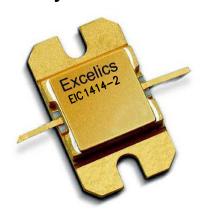


UPDATED 08/20/2007

14.00-14.50GHz 2-Watt Internally-Matched Power FET

FEATURES

- 14.00 -14.50GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +33.5 dBm Output Power at 1dB Compression
- 6.5 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -42 dBc IM3 at Po = 22.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (Ta = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹		TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 14.00-14.50GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550\text{mA}$	32.5	33.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 14.00-14.50GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550\text{mA}$	5.5	6.5		dB
ΔG	Gain Flatness $f = 14.00-14.50 GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550 \text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 550 \text{mA}$ f = 14.00-14.50GHz		30		%
Id_{1dB}	Drain Current at 1dB Compression f = 14.00-14.50GHz		600	700	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 22.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS f = 14.50GHz	-38	-42		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		1040	1440	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 10 \text{ mA}$		-2.5	-4.0	V
R_{TH}	Thermal Resistance ³		11	12	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

3. Overall Rth depends on case mounting.

ABSOLUTE MAXIMUM RATING FOR EFD

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds Drain-Source Voltage		15V	10V	
Vgs	Vgs Gate-Source Voltage		-4V	
lgf	Forward Gate Current	24mA	7.2mA	
lgr	Reverse Gate Current	-4.8mA	-1.2mA	
Pin	Input Power	33.0dBm	@ 3dB Compression	
Tch	Channel Temperature	175C	175C	
Tstg	Storage Temperature	-65C to +175C	-65C to +175C	
Pt Total Power Dissipation		12.5W	12.5W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.



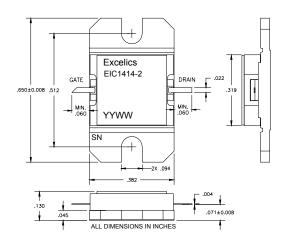
UPDATED 08/20/2007

14.00-14.50GHz 2-Watt Internally-Matched Power FET

PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

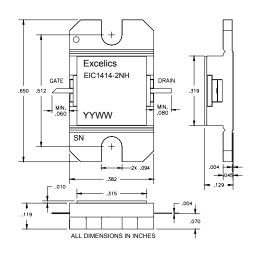
EIC1414-2 (Hermetic)





Caution! ESD sensitive device.

EIC1414-2NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number Packages		Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC1414-2	Hermetic	Industrial	14.00-14.50GHz	32.5	-38
EIC1414-2NH	Non-Hermetic	Industrial	14.00-14.50GHz	32.5	-38

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness